



Specification of Automotive MLCC

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- A. Samsung Part Number

- Samsung P/N : CL21C470JB61PNC
- Description : CAP, 47 pF, 50V, ±5%, C0G, 0805
- AEC-Q 200 Specified

		<mark>CL</mark> ①	<mark>21</mark> ②	<u>C</u> 3	<u>470</u> (4)	<u>J</u> (5)	<u>B</u> 6	<mark>6</mark> 7	<u>1</u> ®	<u>P</u> 9	<u>N</u> 10	<u>C</u> 10
1	Series	Samsung Multi-layer Ceramic Capacitor										
2	Size	0805 (inch co	ode)		L:	2.0	± 0.1	mm			W:	1.25 ± 0.1 mm
3	Dielectric	C0G				8	Inner	electr	ode			Ni
4	Capacitance	47 pF					Termi	natior	า			Cu
(5)	Capacitance	±5 %					Platin	g				Sn 100% (Pb Free)
	tolerance					9	Produ	ict				Automotive
6	Rated Voltage	50 V				10	Grade	code				Standard
\bigcirc	Thickness	0.6 ± 0.1	mm			1	Packa	ging				Cardboard Type, 7" reel

B. Reliablility Test and Judgement condition

	Performance	Test condition				
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150 °C				
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion				
	within ±2.5% or ±0.25 ${}_{\text{p}}{}^{\text{F}}$ whichever is larger					
	Q : 1000 min					
	IR : More than 10,000 M or 500 M $\times \mu F$					
	Whichever is Smaller					
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles				
	Capacitance Change :	Measurement at 24±2hrs after test conclusion				
	within ±2.5% or ±0.25 ${}_{\text{p}}\text{F}$ whichever is larger	1 cycle condition :				
	Q : 1000 min	-55+0/-3 ℃(15±3min) -> Room Temp(1min.)				
	IR : More than 10,000 M or 500 M $\times \mu F$	-> 125+3/-0 °C (15±3min) -> Room Temp(1min.)				
	Whichever is Smaller					
Destructive Physical	No Defects or abnormalities	Per EIA 469				
Analysis						
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle				
	Capacitance Change :	Heat (25~65 $^\circ\!\!\mathrm{C}$) and humidity (80~98%), Unpowered				
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	measurement at 24±2hrs after test conclusion				
	Q : 350 min					
	IR : More than 10,000 M or $500 M \times \mu F$					
	Whichever is Smaller					
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85 ℃/85%RH, Rated Voltate and 1.3~1.5V,				
	Capacitance Change :	Add 100kohm resistor				
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	Measurement at 24±2hrs after test conclusion				
	Q : 200 min	The charge/discharge current is less than 50mA.				
	IR : More than 500M Ω or 25M Ω × μ F					
	Whichever is Smaller					
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125 °C, 200% Rated Voltage,				
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion				
	within $\pm 3.0\%$ or ± 0.3 pF whichever is larger	The charge/discharge current is less than 50mA.				
	Q : 350 min					
	IR : More than 10,000M Ω or 500M Ω × μ F					
	Whichever is Smaller					

	Performance	Test condition					
External Visual	No abnormal exterior appearance	Microscope (´10)					
Physical Dimensions	Within the specified dimensions	Using The calipers					
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along					
	Capacitance Change :	3 mutually perpendicular axes of the test specimen (18 shocks)					
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Peakvalue Duration Wave Velocity					
	Q, IR : initial spec.	1,500G 0.5ms Half sine 4.7m/sec.					
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,					
	Capacitance Change :	Use 8"x5" PCB 0.031" Thick 7 secure points on one long side					
	within ±2.5% or ±0.25pF whichever is larger	and 2 secure points at corners of opposite sides. Parts mounted					
	Q, IR : initial spec.	within 2" from any secure point. Test from $10~2000 \text{Hz}$.					
Resistance to	Appearance : No abnormal exterior appearance	Solder pot : 260±5°C, 10±1sec.					
Solder Heat	Capacitance Change :						
	within ±2.5% or ±0.25 ${\mbox{\tiny p}}{\mbox{\tiny F}}$ whichever is larger						
	Q, IR : initial spec.						
Thermal Shock	Appearance : No abnormal exterior appearance	-55℃/+125℃.					
	Capacitance Change :	Note: Number of cycles required-300,					
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	Maximum transfer time-20 sec, Dwell time-15min. Air-Air					
	Q, IR : initial spec.						
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002					
	Capacitance Change :						
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger						
	Q, IR : initial spec.						
Solderability	95% of the terminations is to be soldered	a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 245±5 °C					
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C					
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 $^\circ \rm C$					
		solder : a solution ethanol and rosin					
Electrical	Capacitance : Within specified tolerance	The Capacitance /Q should be measured at 25 °C,					
Characterization	Q : 1000 max.	1Mb±10%, 0.5~5Vrms					
	IR(25℃) : More than 100,000№ or 1,000№×µF	I.R. should be measured with a DC voltage not exceeding					
	IR(125 °C) : More than10,000 № or 100 № ×μF	Rated Voltage @25°C, @125°C for 60~120 sec.					
	Whichever is Smaller	Dielectric Strength : 250% of the rated voltage for 1~5 seconds					
Description	Dielectric Strength	Dending to the light (0 -) for 5 accords					
Board Flex	Appearance : No abnormal exterior appearance	Bending to the limit (3mm) for 5 seconds					
	Capacitance Change :						
Terminal	within ±5.0% or ±0.5pF whichever is larger Appearance : No abnormal exterior appearance	18N, for 60±1 sec.					
Strength(SMD)	Capacitance Change :						
	within $\pm 2.5\%$ or $\pm 0.25pF$ whichever is larger						
Beam Load	Destruction value should not be exceed	Beam speed					
Evan Evan	Chip Length < 2.5mm	0.5±0.05mm/sec					
	a) Chip Thickness > 0.5mm : 20N						
	b) Chip Thickness ≤ 0.5 mm : 20N						
Temperature	COG						
Characterisitcs	(From -55 ℃ to 125℃, Capacitance change shoud	be within +30PPM/°C)					
ondiaotori 3103	(1011 00 0 to 120 0, oapacitance change shoud						

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^\circ\!\!C$, 10sec. Max) Meet IPC/JEDEC J-STD-020 D Standard

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.